

TOSHIBA HIGH EFFICIENCY RECTIFIER SILICON EPITAXIAL TYPE

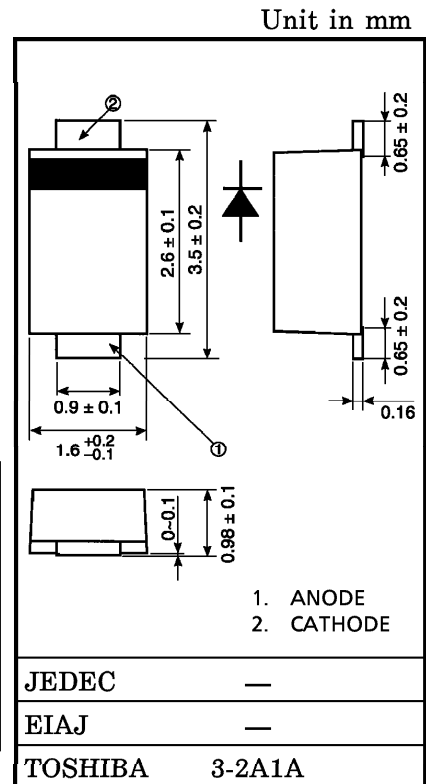
# CRH01

SWITCHING TYPE POWER SUPPLY APPLICATIONS

- Repetitive Peak Reverse Voltage :  $V_{RRM} = 200\text{ V}$
- Average Forward Current :  $I_F (AV) = 1.0\text{ A}$
- Low Forward Voltage :  $V_{FM} = 0.98\text{ V (Max.)}$
- Very Fast Reverse-Recovery Time :  $t_{rr} = 35\text{ ns (Max.)}$
- Small & Thin Package : **S-FLAT™**  
(Toshiba Package Name)

**MAXIMUM RATINGS**

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	$V_{RRM}$	200	V
Average Forward Current	$I_F (AV)$	1.0	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	$I_{FSM}$	15 (50 Hz)	A
Junction Temperature	$T_j$	-40~150	°C
Storage Temperature Range	$T_{stg}$	-40~150	°C



Weight : 0.013 g

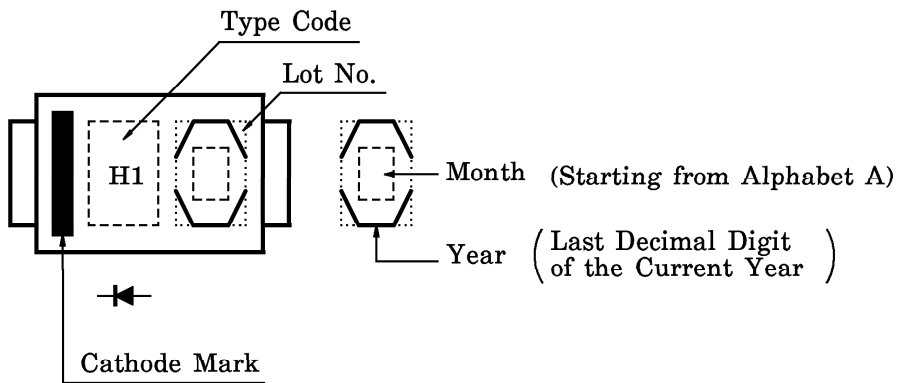
**ELECTRICAL CHARACTERISTICS (Ta = 25°C)**

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Peak Forward Voltage	$V_{FM} (1)$	$I_{FM} = 0.1\text{ A}$	—	0.71	—	V
	$V_{FM} (2)$	$I_{FM} = 0.7\text{ A}$	—	0.86	—	
	$V_{FM} (3)$	$I_{FM} = 1.0\text{ A}$	—	0.90	0.98	
Repetitive Peak Reverse Current	$I_{RRM}$	$V_{RRM} = 200\text{ V}$	—	—	10	$\mu\text{A}$
Reverse Recovery Time	$t_{rr}$	$I_F = 1\text{ A}, di/dt = -30\text{ A}/\mu\text{s}$	—	—	35	ns
Forward Recovery Time	$t_{fr}$	$I_F = 1\text{ A}$	—	—	100	ns
Thermal Resistance	$R_{th} (j-a)$	On ceramic substrate	—	—	65	°C / W
		On glass-epoxy substrate	—	—	130	

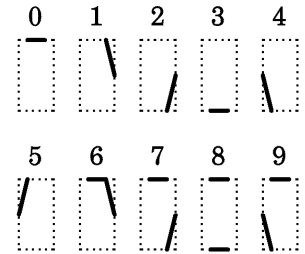
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MARKING



FOLLOWING INDICATES THE DATE OF MANUFACTURE



STANDARD SOLDERING PAD

Unit : mm

